| PCN Number: | 20230324001.0 | | PCN Date: | April 04, 2023 |
|---|---|---|---|---|
| **Title:** | Top side marking change for Select Devices | | | |
| **Customer Contact:** | PCN Manager | **Dept:** | Quality Services | |

**Change Type:**

| | | | | | | |
|---|---|---|---|---|---|---|
| ☐ | Assembly Site | ☐ | Design | ☐ | Wafer Bump Material |
| ☐ | Assembly Process | ☐ | Data Sheet | ☐ | Wafer Bump Process |
| ☐ | Assembly Materials | ☐ | Part number change | ☐ | Wafer Fab Site |
| ☐ | Mechanical Specification | ☐ | Test Site | ☐ | Wafer Fab Materials |
| ☒ | Packing/Shipping/Labeling | ☐ | Test Process | ☐ | Wafer Fab Process |

## PCN Details

**Description of Change:**

This notice is to communicate an update in the device symbolization format for the devices in the product affected selection as follows:

| Material name | Current | New |
|---|---|---|
| CSD25211W1015 | 25211<br>XXXXX<br>O<br><br>XXXXX = LAST 5 CHARACTER OF DIE LOT NUMBER<br>O = PIN 1 INDICATOR | 25211<br>$$YMD<br>O<br><br>YM = YEAR MONTH DATE CODE<br>D = DAY OF LASER MARK<br>$$ = FAB CODE<br>O = PIN 1 INDICATOR |
| CSD86311W1723 | O<br>86311<br>XXXXX<br><br>XXXXX = LAST 5 CHARACTER OF DIE LOT NUMBER<br>O = PIN 1 INDICATOR | O<br>86311<br>$$YMD<br><br>YM = YEAR MONTH DATE CODE<br>D = DAY OF LASER MARK<br>$$ = FAB CODE<br>O = PIN 1 INDICATOR |

**Reason for Change:**

Improved device traceability

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

Device symbolization

**Product Affected:**

| CSD25211W1015 | CSD86311W1723 |
|---|---|

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|---|---|
| WW PCN Team | PCN_ww_admin_team@list.ti.com |

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